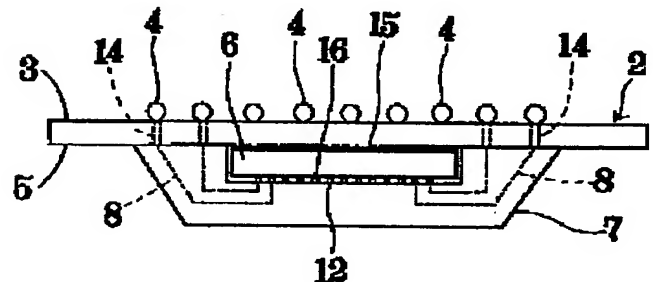
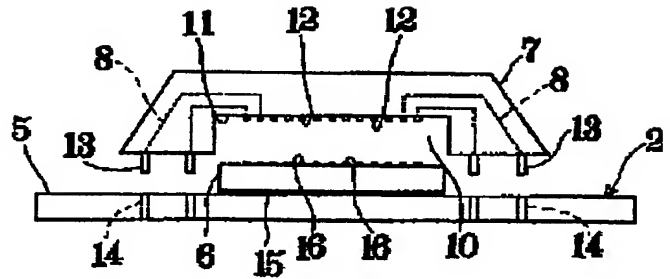


# Pat nt Abstracts of Japan

**TITLE : BGA SEMICONDUCTOR PACKAGE STRUCTURE**



**SOLUTION:** A plastic case 7 is made to cover on a chip 6, the chip 6 is made to closely adhere to a substrate 2 to pressure-bond conducting needles 12 to bumps 16 formed on the upper surface of the chip 6 and the bumps 16, and the needles 12 are conducted to each other. Then, the substrate 2 is inverted, solder balls 4 covered with a flux are placed on the open parts of fitting holes 14 to fuse the balls 4, and the balls 4 are made to have continuity with conducting terminals 13. As a result, as the chip 6 and the balls 4 are connected with each other via wires 18, a wire bonding process which is hitherto executed, is dispensed with, the connection of the chip 6 with the substrate 2 can be reliably made and the production process of a BGA type semiconductor package structure can be simplified.

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